

Product Change Notification - KSRA-20CIED111

Date: 29 Jun 2017
Product Category: 16-Bit - Microcontrollers and Digital Signal Controllers; 8-bit PIC Microcontrollers
Notification subject: CCB 3014 Initial Notice: Qualification of CuPdAu bond wire in selected products for 160K wafer technology available in 44L QFN (8x8x0.9mm) package at NSEB assembly site
Notification text: **PCN Status:**
 Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products for 160K wafer technology available in 44L QFN (8x8x0.9mm) package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire, 8200T or 8600 die attach, G770HCD or G700LTD mold compound material, and C194 or AgCu lead frame material.

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach, G700LTD mold compound material, C194 lead frame material.

Pre and Post Change Summary:

	Pre Change		Post Change
Assembly Site	NSEB Assembly Site		NSEB Assembly Site
Wire material	Au Wire		CuPdAu Wire
Die attach material	8200T	8600	8600
Molding compound material	G770HCD	G700LTD	G700LTD
Lead frame material	AgCu	C194	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability and qualify CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

December 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been

issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

Workweek	June 2017					-->	December 2017				
	22	23	24	25	26		49	50	51	52	53
Initial PCN Issue Date					X						
Qual Report Availability									X		
Final PCN Issue Date									X		

Method to Identify Change:
Traceability code

Qualification Plan:
Please open the attachments included with this PCN labeled as PCN_#_Qual Plan

Revision History:
June 29, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN_KSRA-20CIED111_Affected CPN.pdf](#)
 - [PCN_KSRA-20CIED111_Qual Plan.pdf](#)
 - [PCN_KSRA-20CIED111_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-20CIED111
CATALOG_PART_NBR
DSPIC30F2023-20E/ML
DSPIC30F2023-30I/ML
DSPIC30F2023T-30I/ML
DSPIC30F2023T-30V/MLD31
DSPIC30F3010-20I/ML
DSPIC30F3010-30I/ML
DSPIC30F3010T-30I/ML
DSPIC30F3011-10I/MLB24
DSPIC30F3011-20E/ML
DSPIC30F3011-20I/ML
DSPIC30F3011-30I/ML
DSPIC30F3011T-10I/MLB21
DSPIC30F3012-20E/ML
DSPIC30F3012-20I/ML
DSPIC30F3012-30I/ML
DSPIC30F3012T-20I/ML
DSPIC30F3013-20E/ML
DSPIC30F3013-20I/ML
DSPIC30F3013-30I/ML
DSPIC30F3013-30I/MLB31
DSPIC30F3013T-20I/ML
DSPIC30F3013T-30I/ML
DSPIC30F3013T-30I/MLB31
DSPIC30F3014-20E/ML
DSPIC30F3014-20I/ML
DSPIC30F3014-30I/ML
DSPIC30F3014-30I/MLA31
DSPIC30F3014T-30I/MLA31
DSPIC30F4011-20E/ML
DSPIC30F4011-20I/ML
DSPIC30F4011-30I/ML
DSPIC30F4012-20E/ML
DSPIC30F4012-20I/ML
DSPIC30F4012-30I/ML
DSPIC30F4013-20E/ML
DSPIC30F4013-20I/ML
DSPIC30F4013-30I/ML
DSPIC30F4013-30I/MLB31
DSPIC30F4013T-30I/ML
DSPIC30F4013T-30I/MLB31
PIC16F884-E/ML
PIC16F884-I/ML
PIC16F884T-I/ML

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PCN_KSRA-20CIED111
CATALOG_PART_NBR
PIC16F887-E/ML
PIC16F887-I/ML
PIC16F887T-I/ML
PIC16F914-E/ML
PIC16F914-I/ML
PIC16F914T-I/ML
PIC16F917-E/ML
PIC16F917-I/ML
PIC16F917T-I/ML
PIC18F4221-E/ML
PIC18F4221-I/ML
PIC18F4321-E/ML
PIC18F4321-I/ML
PIC18F4410-E/ML
PIC18F4410-I/ML
PIC18F4420-E/ML
PIC18F4420-I/ML
PIC18F4420T-I/ML
PIC18F4423-E/ML
PIC18F4423-I/ML
PIC18F4423T-I/ML
PIC18F4450-I/ML
PIC18F4455-I/ML
PIC18F4455T-I/ML
PIC18F4458-I/ML
PIC18F4480-E/ML
PIC18F4480-I/ML
PIC18F4480T-I/ML
PIC18F4510-E/ML
PIC18F4510-I/ML
PIC18F4510T-I/ML
PIC18F4515-I/ML
PIC18F4520-E/ML
PIC18F4520-I/ML
PIC18F4520T-E/ML
PIC18F4520T-I/ML
PIC18F4523-E/ML
PIC18F4523-I/ML
PIC18F4523T-I/ML
PIC18F4525-E/ML
PIC18F4525-I/ML
PIC18F4525T-I/ML
PIC18F4550-I/ML

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PCN_KSRA-20CIED111
CATALOG_PART_NBR
PIC18F4550T-I/ML
PIC18F4553-I/ML
PIC18F4580-E/ML
PIC18F4580-I/ML
PIC18F4580T-I/ML
PIC18F4585-E/ML
PIC18F4585-H/ML
PIC18F4585-I/ML
PIC18F4585-I/MLC01
PIC18F4585T-I/ML
PIC18F4610-I/ML
PIC18F4620-E/ML
PIC18F4620-I/ML
PIC18F4620T-I/ML
PIC18F4680-E/ML
PIC18F4680-H/ML
PIC18F4680-I/ML
PIC18F4680T-I/ML
PIC18F4682-E/ML
PIC18F4682-I/ML
PIC18F4685-E/ML
PIC18F4685-I/ML
PIC18F4685T-I/ML
PIC18LF4221-I/ML
PIC18LF4221T-I/ML
PIC18LF4321-I/ML
PIC18LF4410-I/ML
PIC18LF4420-I/ML
PIC18LF4420T-I/ML
PIC18LF4423-I/ML
PIC18LF4423T-I/ML
PIC18LF4450-I/ML
PIC18LF4450T-I/ML
PIC18LF4455-I/ML
PIC18LF4455T-I/ML
PIC18LF4458-I/ML
PIC18LF4480-I/ML
PIC18LF4480T-I/ML
PIC18LF4510-I/ML
PIC18LF4510T-I/ML
PIC18LF4515-I/ML
PIC18LF4520-I/ML
PIC18LF4520T-I/ML

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CATALOG_PART_NBR
PIC18LF4523-I/ML
PIC18LF4523T-I/ML
PIC18LF4525-I/ML
PIC18LF4525T-I/ML
PIC18LF4550-I/ML

- PIC18LF4550T-I/ML
- PIC18LF4553-I/ML
- PIC18LF4580-I/ML
- PIC18LF4585-I/ML
- PIC18LF4585T-I/ML
- PIC18LF4610-I/ML
- PIC18LF4620-I/ML
- PIC18LF4620-I/ML035
- PIC18LF4620T-I/ML
- PIC18LF4620T-I/ML035
- PIC18LF4680-I/ML
- PIC18LF4682-I/ML
- PIC18LF4685-I/ML
- PIC18LF4685T-I/ML